KPT-1608SEW-E HYPER ORANGE

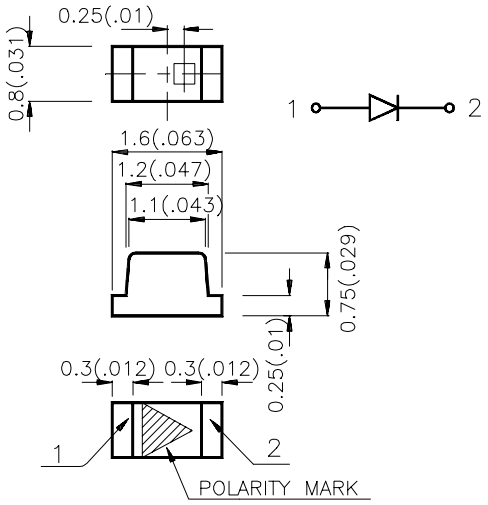
Features

- 1.6mmx0.8mm SMT LED, 0.75mm THICKNESS.
- LOW POWER CONSUMPTION.
- WIDE VIEWING ANGLE.
- IDEAL FOR BACKLIGHT AND INDICATOR.
- VARIOUS COLORS AND LENS TYPES AVAILABLE.
- PACKAGE : 2000PCS / REEL.

Description

The Hyper Orange source color devices are made with DH InGaAlP on GaAs substrate Light Emitting Diode.

Package Dimensions



Notes:
1. All dimensions are in millimeters (inches).
2. Tolerance is ±0.1(0.004") unless otherwise noted.
3. Lead spacing is measured where the lead emerge package.
4. Specifications are subject to change without notice.

Selection Guide

Part No.	Dice	Lens Type	Iv (mcd) @ 20 mA		Viewing Angle
			Min.	Typ.	2θ1/2
KPT-1608SEW-E	HYPER ORANGE (InGaAlP)	WHITE DIFFUSED	60	200	120°

Note:
1. θ1/2 is the angle from optical centerline where the luminous intensity is 1/2 the optical centerline value.

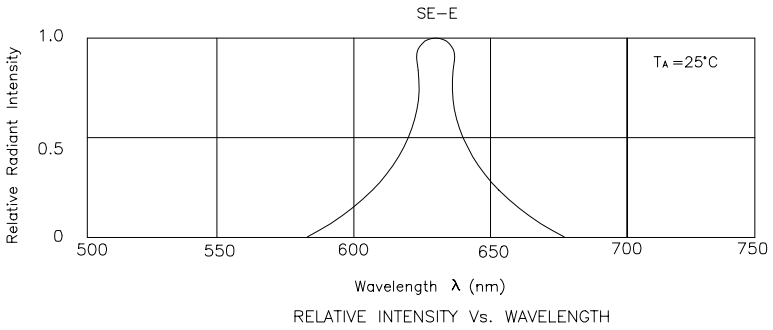
Electrical / Optical Characteristics at T_A=25°C

Symbol	Parameter	Device	Typ.	Max.	Units	Test Conditions
λpeak	Peak Wavelength	Hyper Orange	630		nm	IF=20mA
λ D	Dominate Wavelength	Hyper Orange	621		nm	IF=20mA
Δλ1/2	Spectral Line Halfwidth	Hyper Orange	20		nm	IF=20mA
C	Capacitance	Hyper Orange	25		pF	VF=0V;f=1MHz
V_F	Forward Voltage	Hyper Orange	2.0	2.5	V	IF=20mA
I_R	Reverse Current	Hyper Orange		10	uA	VR = 5V

Absolute Maximum Ratings at T_A=25°C

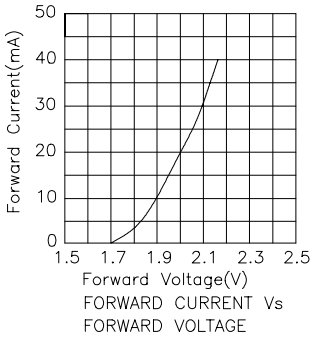
Parameter	Hyper Orange	Units
Power dissipation	150	mW
DC Forward Current	40	mA
Peak Forward Current [1]	195	mA
Reverse Voltage	5	V
Operating Temperature	-40°C To +85°C	
Storage Temperature	-40°C To +85°C	

Note:
1. 1/10 Duty Cycle, 0.1ms Pulse Width.

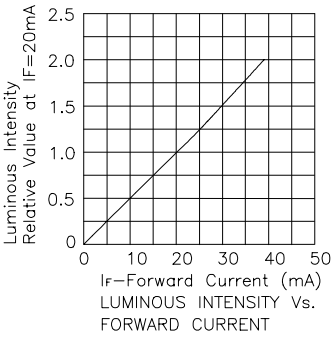


RELATIVE INTENSITY Vs. WAVELENGTH

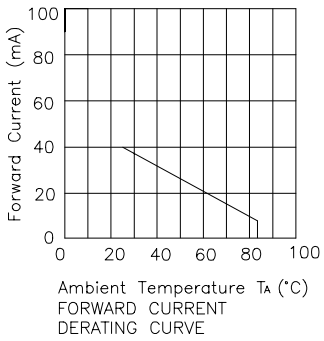
Hyper Orange KPT-1608SEW-E



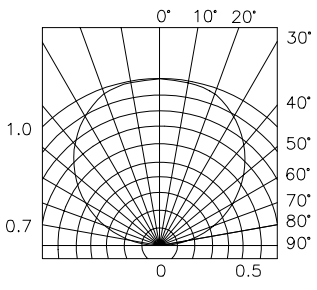
FORWARD CURRENT Vs
FORWARD VOLTAGE



LUMINOUS INTENSITY Vs.
FORWARD CURRENT



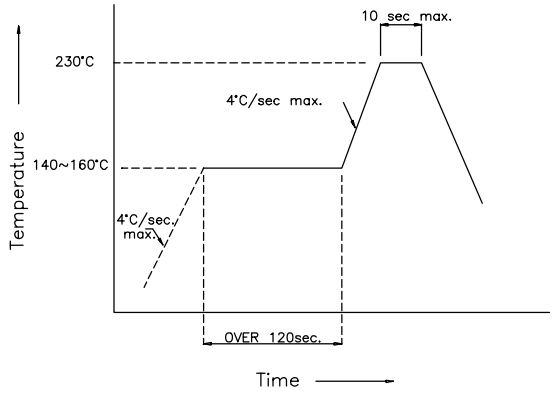
FORWARD CURRENT
DERATING CURVE



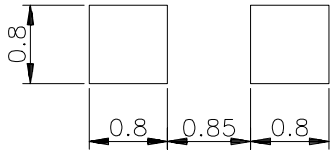
SPATIAL DISTRIBUTION

KPT-1608SEW-E
SMT Reflow Soldering Instructions

Number of reflow process shall be less than 2 times and cooling process to normal temperature is required between first and second soldering process.



Recommended Soldering Pattern (Units : mm)



Tape Specifications (Units : mm)